

# Fulong Zhu

## List of Publications by Year in descending order

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45  
papers

446  
citations

840776

11  
h-index

713466

21  
g-index

45  
all docs

45  
docs citations

45  
times ranked

332  
citing authors

#	ARTICLE	IF	CITATIONS
1	A powder-metallurgy-based strategy toward three-dimensional graphene-like network for reinforcing copper matrix composites. <i>Nature Communications</i> , 2020, 11, 2775.	12.8	137
2	Effects of chirality and number of graphene layers on the mechanical properties of graphene-embedded copper nanocomposites. <i>Computational Materials Science</i> , 2016, 117, 294-299.	3.0	44
3	A molecular dynamic study of nano-grinding of a monocrystalline copper-silicon substrate. <i>Applied Surface Science</i> , 2019, 493, 933-947.	6.1	35
4	Investigation of vibration-assisted nano-grinding of gallium nitride via molecular dynamics. <i>Materials Science in Semiconductor Processing</i> , 2021, 121, 105372.	4.0	28
5	Investigation on gallium nitride with N-vacancy defect nano-grinding by molecular dynamics. <i>Journal of Manufacturing Processes</i> , 2020, 57, 153-162.	5.9	23
6	Investigation of Mechanical Properties of Silicone/Phosphor Composite Used in Light Emitting Diodes Package. <i>Polymers</i> , 2018, 10, 195.	4.5	20
7	Effect of abrasive particle shape on the development of silicon substrate during nano-grinding. <i>Computational Materials Science</i> , 2021, 193, 110420.	3.0	18
8	The effect of contact types on SiC polishing process. <i>Materials Science in Semiconductor Processing</i> , 2022, 147, 106709.	4.0	15
9	Investigation of the Turbulent Drag Reduction Mechanism of a Kind of Microstructure on Riblet Surface. <i>Micromachines</i> , 2021, 12, 59.	2.9	14
10	Removal behavior of micropipe in 4H-SiC during micromachining. <i>Journal of Manufacturing Processes</i> , 2021, 68, 888-897.	5.9	12
11	Effect of inclusion on 4H-SiC during nano-scratching from an atomistic perspective. <i>Journal of Physics Condensed Matter</i> , 2021, 33, 435402.	1.8	12
12	Investigation of microstructures and tensile properties of a Sn-Cu lead-free solder alloy. <i>Journal of Materials Science: Materials in Electronics</i> , 2006, 17, 379-384.	2.2	11
13	Investigation of Nanocutting Characteristics of Off-Axis 4H-SiC Substrate by Molecular Dynamics. <i>Applied Sciences (Switzerland)</i> , 2018, 8, 2380.	2.5	8
14	Investigation of machining mechanism of monocrystalline silicon in nanometric grinding. <i>AIP Advances</i> , 2017, 7, .	1.3	7
15	Ultrasonic power measurement system based on acousto-optic interaction. <i>Review of Scientific Instruments</i> , 2016, 87, 054903.	1.3	6
16	Study on the influence of fretting wear on electrical performance of SMA connector. <i>Microelectronics Reliability</i> , 2021, 118, 114047.	1.7	6
17	Investigation of Thermal Properties of Ni-Coated Graphene Nanoribbons Based on Molecular Dynamics Methods. <i>Journal of Electronic Materials</i> , 2017, 46, 4733-4739.	2.2	5
18	Investigation Regarding the Influence of Contact Condition on the Thermal Contact Resistance Between Copper and Indium. <i>IEEE Transactions on Electron Devices</i> , 2021, 68, 4028-4032.	3.0	5

#	ARTICLE	IF	CITATIONS
19	Comparing the copper and gold wire bonding during thermalsonic wire bonding process. , 2016, , .		4
20	Study on subsurface damage of wafer silicon containing through silicon via in thinning. European Physical Journal Plus, 2019, 134, 1.	2.6	4
21	Warpage measurement of various substrates based on white light shadow moiré technology. , 2011, , .		3
22	An adjustable sensitivity shadow moiré technique for surface morphology measurement. Journal of Modern Optics, 2014, 61, 641-649.	1.3	3
23	Comparison of ultrasonic wire bonding process between gold and copper by nonlinear structure analysis. Journal of Adhesion Science and Technology, 2018, 32, 2007-2018.	2.6	3
24	Morphology Evaluation of Microelectronic Packaging Substrates Using Shadow Moiré Technique. IEEE Access, 2018, 6, 33099-33110.	4.2	3
25	Effects of Chirality and Position of Graphene on the Bending Properties of Graphene-Embedded Copper Nanocomposites. Journal of Nanoscience and Nanotechnology, 2017, 17, 3105-3110.	0.9	3
26	Deformation mechanism of copper reinforced by three-dimensional graphene under torsion and tension. Modelling and Simulation in Materials Science and Engineering, 2022, 30, 025004.	2.0	3
27	Automatic seepage detection in cable tunnels using infrared thermography. Measurement Science and Technology, 2019, 30, 115902.	2.6	2
28	Design and Optimization of a Novel MEMS Tuning Fork Gyroscope Microstructure. Micromachines, 2022, 13, 172.	2.9	2
29	Convolutional Neural Network with Attention Module for Identification of Tunnel Seepage. Transportation Research Record, 0, , 036119812210917.	1.9	2
30	Molecular Dynamics Study of Compressive Properties and Atomistic Behavior of Boron Nitride Nanosheets Reinforced in Aluminum Matrix Composites. Jom, 2022, 74, 3518-3530.	1.9	2
31	Mechanical properties investigation of graphene coated with Ni. , 2013, , .		1
32	Estimation of homogenized Young's modulus of silicone/phosphor composite considering random dispersion and size variation of phosphor particles. Journal of Composite Materials, 2016, 50, 1981-1988.	2.4	1
33	An accurate method to calibrate shadow moiré measurement sensitivity. Measurement Science and Technology, 2019, 30, 125021.	2.6	1
34	Investigation on Thermal Contact Resistance Between Indium and Cap in Packaging. , 2019, , .		1
35	Accuracy optimization method of ultrasonic power measurement system based on acousto-optic effect. Optical Review, 2021, 28, 207-214.	2.0	1
36	Mechanical Response of BNNS-reinforced Aluminum Composites under Uniaxial Compression. , 2021, , .		1

#	ARTICLE	IF	CITATIONS
37	Mechanical stretching behavior simulation of SWCNT and SWCNT-Ni. , 2011, , .		0
38	Tensile behaviors investigation of SWCNT-Ni with vacancies. , 2012, , .		0
39	Compressing deformation investigation of single-walled carbon nanotube coated with Ni. , 2012, , .		0
40	Molecular Dynamics Simulation of GaN Nano-grinding. , 2018, , .		0
41	Molecular Dynamics Simulation on Grinding Process of Cu-Si and Cu-SiO <sub>2</sub> Composite Structures. , 2018, , .		0
42	Thermal Conductivity Investigation of Phosphor/Silicone Composites. , 2019, , .		0
43	Investigation on the Interface Thermal Resistance of Copper-Titanium. , 2019, , .		0
44	Investigation on Contact Resistance of Connector Based on FEM. , 2020, , .		0
45	Molecular dynamics study of BNNS/Al composites under compression. , 2021, , .		0